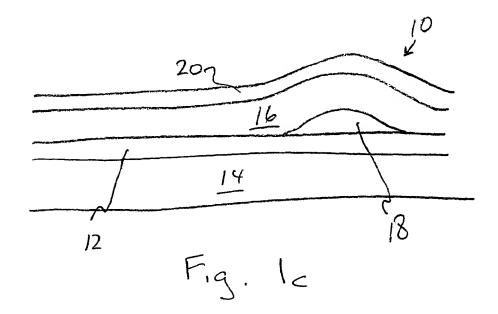
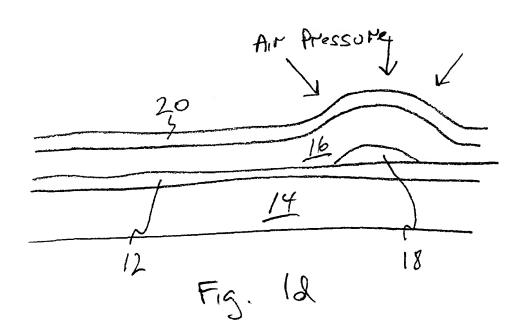
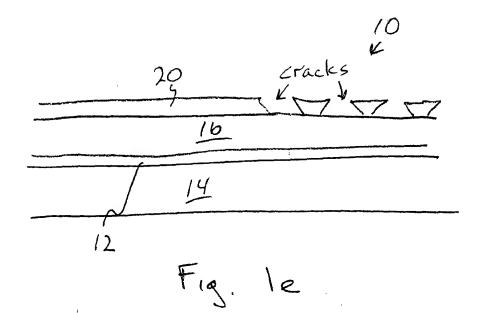


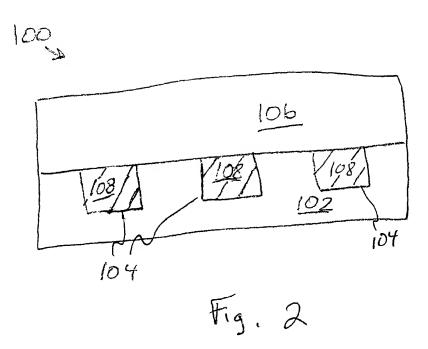
Fig. 16

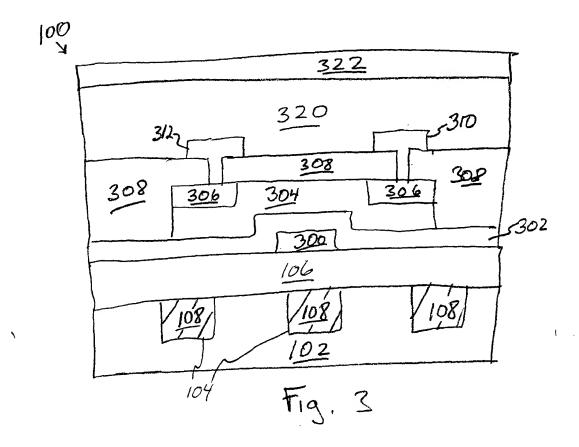


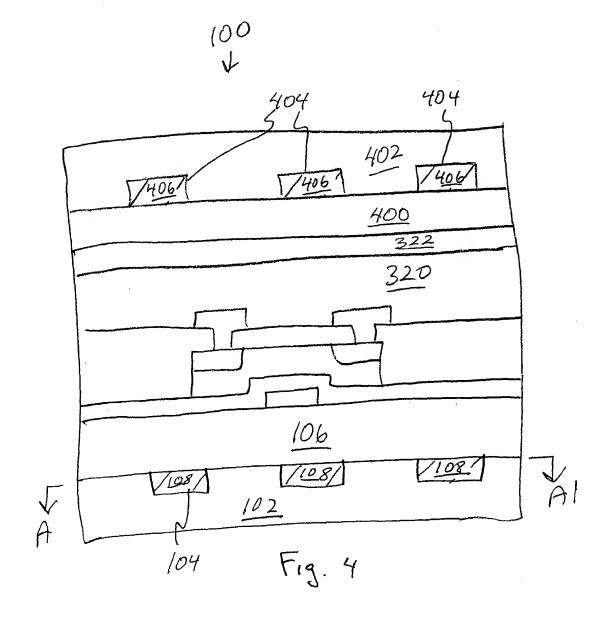


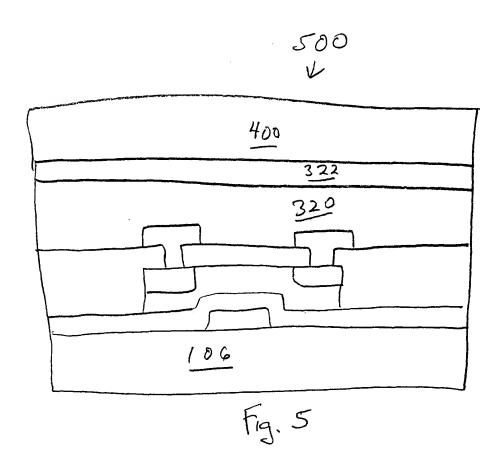
0

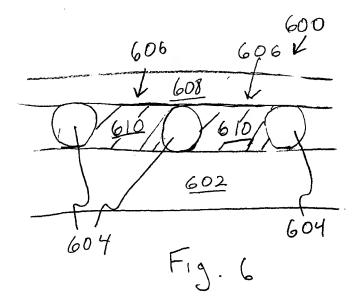












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Fig. 7

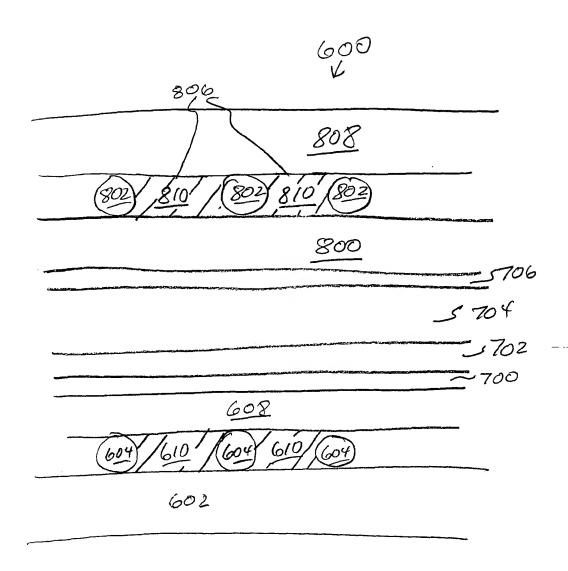


Fig. 8

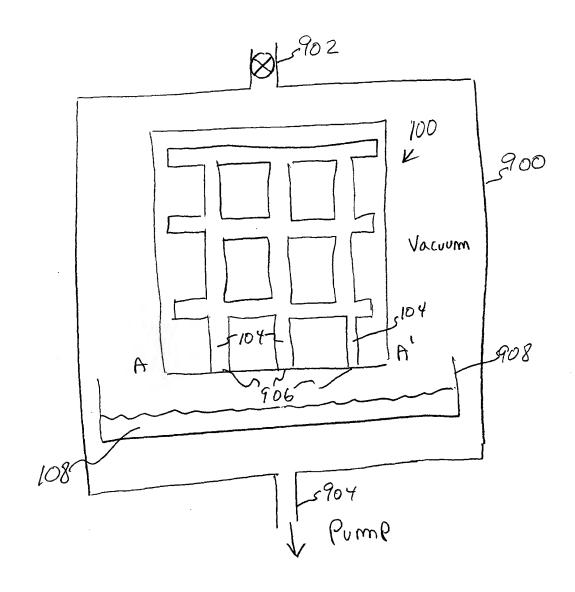


Fig. 9a

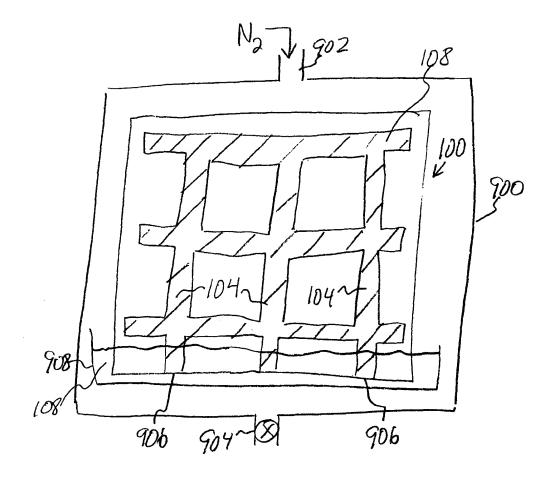


Fig. 96

		, 1000
Fig. 10	Start)	100 2
forming	risid support	substrate)
Erming	flexible sub	strate 1504
	ng adhesive f	
	yacuum)	1006a 1006b
	ing adhesive t	o trench mouth
Pulling	adhesive into	Trench 1006c
	adhesive 10	08 1010
Ide posi-		$\frac{3}{mc}$
Hormin		2-1012
Hormin		1014 ter 1016
Formin	of flexible so	5 55trate 10,18
Hormin	15 risid sup	port substrate
Tinsea	ting adhesiv	e 1020
TCUT!	ns odhesiv	
Ldet	raching Suppo	rt substrate

1100 Fig. START SON Misid support substrate Cormina 06 forming flexibe substrate insecting adhesive 75/108 Creating Vacuum Supplying glue to spacer channels 1108cz/returning to ambient pressure 1108d & Pulling adhesive into spacer channel 11110 Curing adhesive depositing forming forming color filter flexible Substrate to rming distributing spacersts rigid support substrate torming adhesive/1124 adhesive 751126 detacting support substrate